

7676C (.760" x .760")

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Product Features

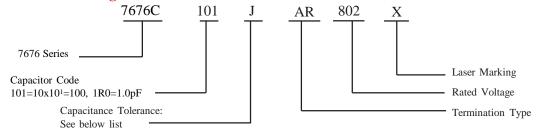
High Q, High RF Current/Voltage, High RF Power, Low ESR/ESL, Low Noise, Ultra-Stable Performance



♦ 7676C Capacitance Table

Cap. pF	Code	Tol.	Rated WVDC	Cap. pF	Code	Tol.	Rated WVDC	Cap. pF	Code	Tol.	Rated WVDC
1.0	1R0			33	330			1000	102		
1.2	1R2			39	390		5000V Code 502;	1200	122		
1.5	1R5			47	470			1500	152		
1.8	1R8			56	560			1800	182		3000V Code 302;
2.2	2R2	D.C.D.		68	680			2200	222		Extended
2.7	2R7	B,C,D		82	820		Extended	2700	272		5000V
3.3	3R3		5000V Code 502; Extended	100	101		8000V Code 802	3300	332		Code 502
3.9	3R9			120	121	Code 802 F,G,		4700	472	G,	
4.7	4R7			150	151			5100	512		
5.6	5R6		8000V	180	181	J,K		5600	562	J,K	
6.8	6R8		Code 802	220	221			6800	682		1000V Code 102; Extended
8.2	8R2			270	271			7500	752		
10	100			300	301			8200	822		3000V
12	120	F,G, J,K		390	391		3000V Code 302;	10000	103		Code 302
15	150			470	471		Extended 5000V	12000	123		100075
18	180			560	561			15000	153		1000V Code 102;
22	220			680	681		Code 502	18000	183		2000V
27	270			820	821			20000	203		Code202

♦ Part Numbering



Capacitance Tolerance									
Code	Code B C D F G J K								
Tolerance	±0.1pF	±0.25pF	±0.5pF	±1%	±2%	±5%	±10%		



♦ 7676C Lead Type and Dimensions

7676C (.760" x .760")

unit: inch (millimeter)

			Capacitor Dimensions			Lead Dimensions				
Series	Term. Code	Type/ Outlines	Length Lc	Width Wc	Thick -ness Tc	Overlap B	Length LL	Width WL	Thick- ness TL	Plated Material
7676C	W L	Chip				.063 (1.60) max	-	-	-	Nickel Plating RoHS Compiliant 90% Sn10% Pb Tin/Lead Solder over Nickel Plating
7676C	MS	Microstrip	.760 +.015	.760 ±.010 (19.3± 0.25)	.154 ± .008 (3.90 ±0.20)	-	.787 (20.00) min	.591 ± .010 (15.0± 0.25)	.008 ± .001 (0.20± 0.025)	Silver- plated
7676C	AR	Axial Ribbon	to 010 (19.3 +0.38 to							
7676C	RW	Radial Wire	-0.25)				.787 (20.00) min	Dia.= .03±.004 0.80 ± 0.10		Copper
7676C	AW	Axial Wire					1.181 (30.00)			
	_	71	Capacitor Dimensions				Lead Dimensions			Plated
Series	Term. Code		Length Lc	Width Wc	Thick -ness Tc	Overlap B	Length LL	Width WL	Thick- ness TL	Material
7676C	P	The Chip (Non-Mag)				.063 (1.60) max	ı	ı	ı	100% Sn Solder over Copper Plating
7676C	MN	Microstrip(Non-Mag)	.760 +.015 to	.760 ±.010	.154 ±		.787 (20.00)	.591 ± .010	.008 ±.00 1	
7676C	AN	Axial Ribbon (Non-Mag)	010 (19.3 +0.38 to	(19.3± 0.25)	.008 (3.90 ±0.20)	-	min	(15.0± 0.25)	(0.20 ± 0.025)	Silver- plated
7676C	RN	Radial Wire (Non-Mag)	-0.25)				.787 (20.00) min	Dia.= $.03 \pm .004$ 0.80 ± 0.10		Copper
7676C	BN	Axial Wire (Non-Mag)					1.181 (30.00) min			

Note: "Non-Mag" means no magnetic materials. All leads are attached with high temperature solder and parts are RoHS Compliant.



Performance

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Item	Specifications					
Quality Factor (Q)	No less than 1000pF, Q value more than 2000, Test frequency 1MHz; More than 1000pF, Q value more than 2000, Test frequency 1KHz					
Insulation Resistance (IR)	Test Voltage: 500V: 10 ⁵ Megaohms min. @ +25°C at rated WVDC 10 ⁴ Megaohms min. @ +125°C at rated WVDC					
Rated Voltage	See Rated Voltage Table					
Dielectric Withstanding Voltage (DWV)	250% of Voltage for 5 seconds, Rated Voltage ≤ 500 VDC 150% of Voltage for 5 seconds, 500 VDC <rated vdc<br="" voltage="" ≤1250="">120% of Voltage for 5 seconds, Rated Voltage > 1250VDC</rated>					
Operating Temperature Range	-55°C to +175°C					
Temperature coefficient (TC)	$0 \pm 30 \text{ppm/}^{\circ}\text{C}$					
Capacitance Drift	±0.02% or ±0.02pF, whichever is greater					
Piezoelectric Effects	None					

Capacitors are designed and manufactured to meet the requirements of MIL-PRF-55681 and MIL-PRF-123.

♦ Environmental Tests

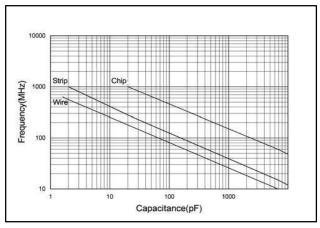
Item	Specifications	Method					
Thermal shock	DWV: the initial value IR: Shall not be less than 30% of the initial value. Capacitance change:	MIL-STD-202, Method 107, Condition A At the maximum rated temperature (-55°C and 125°C) stay 30 min, the time of removing shall not be more than 3 minutes. Perform the five cycles.					
Moisture resistance	no more than 0.5% or 0.5 pF, whichever is greater.	MIL-STD-202, Method 106					
Humidity (steady state)	DWV: the initial value IR: the initial value Capacitance change: no more than 0.3% or 0.3pF, whichever is greater.	MIL-STD-202, Method 103, Condition A With 1.5 Volts DC applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours minimum					
Life	IR: Shall not be less than 30% of the initial value. Capacitance change: no more than 2.0% or 0.5 pF, whichever is greater.	MIL-STD-202, Method 108, for 2000 hours at 125°C 200% of Voltage for Capacitors, Rated Voltage ≤500 VDC 120% of Voltage for Capacitors, 500 VDC <rated 100%="" capacitors,="" for="" of="" rated="" voltage="" ≤1250vdc=""> 1250VDC</rated>					
Terminal strength	Force: 30lbs typical, Duration time: 5 to 10 seconds.	MIL-STD-202, Method 211A, Test condition A Applied a force and maintained for a period of 5 to 10 seconds. The force shall be in the direction of the axes of the terminations.					



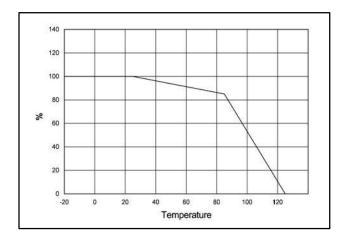
♦ 7676C Performance Curves

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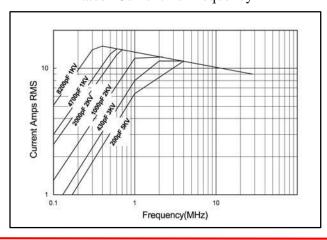
Self Resonant Frequency vs Capacitance



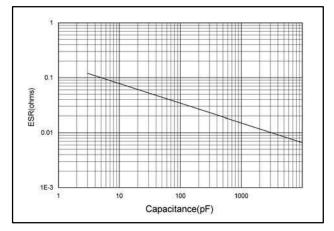
% Maximum Current vs Ambient Temperature



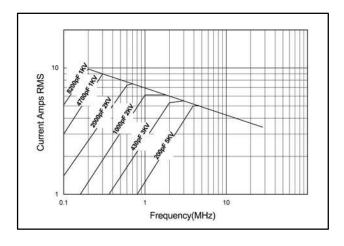
7676C Strip Terminals Rated Current vs Frequency



ESR vs Capacitance measured @ 30MHz



7676C Wire Terminals Rated Current vs Frequency







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PPI7676CDATA041819RevA

♦ Recommended Land Pattern Dimensions

When mounting the capacitor to substrate, it's important to carefully consider that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it's mounted.

- 1) The greater the amount of solder, the greater the stress to the elements. This may cause the substrate to break or crack.
- 2) In the situation where two or more devices are mounted onto a common land, be sure to separate the device into exclusive pads by using soldering resist.

Horizontal Mounting

Orientation	EIA	A	В	С	
Horizontal	7676	16.00	3.30	19.60	

